Build Up HDI (Standard)

HDI08_3+2b+3_1,50_engl

8 - Layers

Core: 0,93 mm Cu 35/35 µm

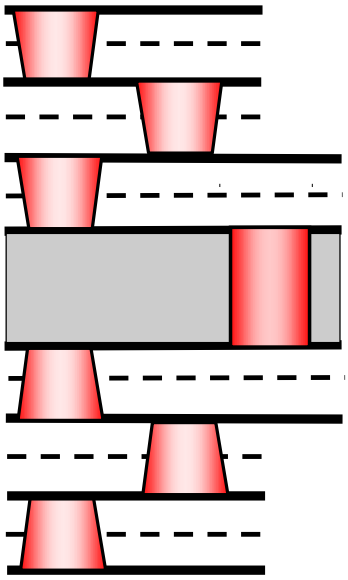
WE-Articel No.:

3 + 2B + 3

Customer:

WÜRTH ELEKTRONIK

only CBT Schopfheim



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		30	
					1 x 1080	60	
	3		Foil	12 µm		30	
					1 x 1080	58	
	4			12 µm		35	
			0,930 mm			930	
	5			12 µm		35	
					1 x 1080	58	
	6		Foil	12 µm		30	
					1 x 1080	60	
	7		Foil	12 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

Gesamtdicke Material: 1500

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,50**	+/-	0,12	mm			Date: / Engineer:
thickness with electro plated Cu:	1,59	+/-	0,15	mm			
total thickness with soldermask	1,65	+/-	0,17	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision		
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page:	23+